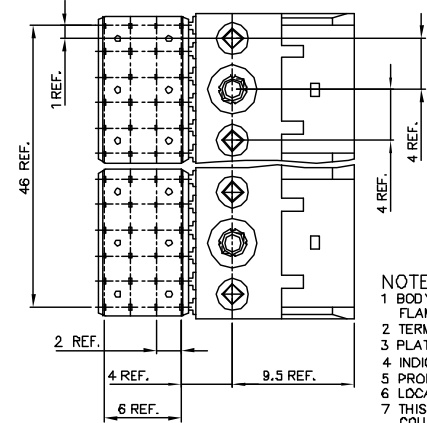
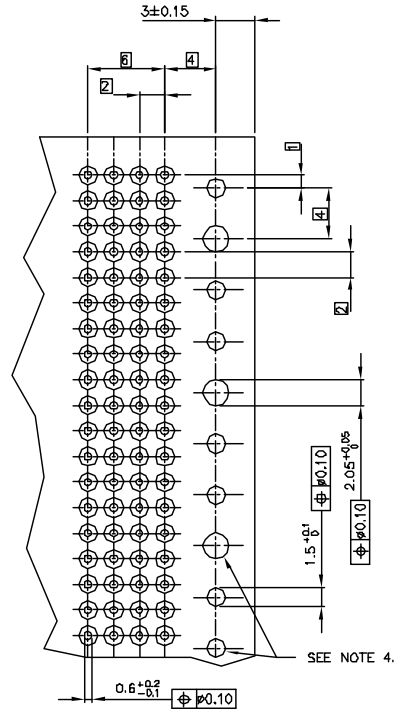
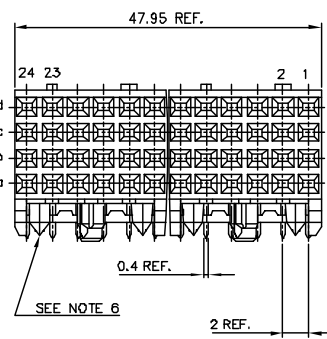
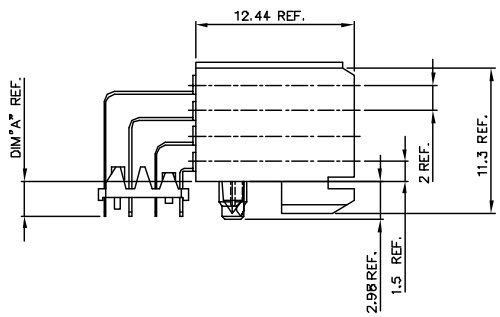
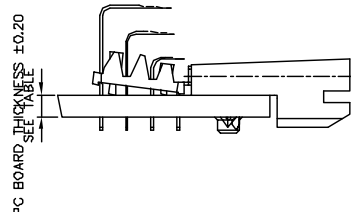


PC BOARD VERSIONS		
PRODUCT NR.	PCB THICKNESS	DIM "A"
89037-X01/X01LF	1.6	2.73
89037-X11/X11LF	2.4	3.53



PRODUCT AFTER PC BOARD APPLICATION.



- NOTES:
- 1 BODY MATL: LIQUID CRYSTAL POLYMER 30% GLASS
FLAME RETARDANT ACC. UL 94-V0
 - 2 TERMINAL MATERIAL: PHOSPHOR BRONZE.
 - 3 PLATING SOLDER TAILS 2-8 μ m SnPb 90-97 OR 2-8 μ m PURE Sn
 - 4 INDICATED HOLES ARE UNPLATED.
 - 5 PRODUCT MARKING: PART NUMBER & BATCH ID.
 - 6 LOCATION PEG FEATURES MAY NOT BE AVAILABLE AS SHOWN.
 - 7 THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.
 - 8 THE HOUSING WILL WITHSTAND EXPOSURE TO 260 DEGREE PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION.

PRODUCT NR.	PLATING CONTACT AREA	UNDERPLATING
89037-1YZ/1YZLF	0.8 μ m GOLD	1.3 μ m Ni MIN.
89037-2YZ/2YZLF	2 μ m GOLD	1.3 μ m Ni MIN.
89037-3YZ/3YZLF	1.3 μ m GOLD	1.3 μ m Ni MIN.
89037-9YZ/9YZLF	0.8 μ m GXT	1.3 μ m Ni MIN.

itr	snr	no	date	linear	projection	customer copy	code
J	004	004	041221				213
D	114336	009	040827	angles			213
F	170299	009	072030	dr	11 BaseMount	030202	213
F	191480	008	190837	dr	11 BaseMount	040201	213
G	190878	014	000318	dr	11 BaseMount	030203	213
H	190847	014	000330	dr	11 BaseMount	030203	213
sheet	index	sheet	1	1	1	1	1

